ABOCIATION CONNECTING LECTRONICS INDUSTRIES® INTERNATIONAL AND ADDRESS INDUSTRIES®	C. Bannock	burn, Illinois, A	ll rights reserved nations.	under both	This docum level parts, t	ent is a declaration er	on of the sub compasses	bstances w all lower	vithin the manufactu level materials for w	rer listed i	tem. Note: nanufacture	if the item is an as r has engineering	sembly with lower responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials ar					ials and M	and Mfg Information			
Supplier Information														
Company name* Com		Company uni	Company unique ID			Unique ID Authority				Response Date*				
nsemi										2025-05	2025-05-11			
Contact Name	tact Name Title - Contact					Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Env			nviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repr			Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Date Version Manufacturing Site		anufacturing Site		Weight*	UOM	Unit Type	
	NVMFS T1G	IVMFS5C410NWFE T6-40V N 0.92 1 1G		Ohms SL		2025-05-11		М	MY1		100.77	mg	Each	
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Ma	terial Terminal Base A		Alloy	by J-STD-020 MSL Rat		Peak Proce	Process Body Temperatu		ure Max Time at Peak Temper		ure Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			260 C		С	30 seco		seconds 3			
Comments														
level 1 - maximum time at peak temperatu	re during so	dering is 10-3	0 seconds											
For more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach Solder	2.33	mg	Supplier	Silver (Ag)	7440-22-4		0.0582	mg
			А	Lead (Pb)	7439-92-1	7a	2.1553	mg
			Supplier	Tin (Sn)	7440-31-5		0.1165	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0286	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.5096	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	42.24	mg		Epoxy resin	proprietary data		3.168	mg
			Supplier	Phenolic Resin	Proprietary Data		1.056	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.168	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.6368	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg